



Attorney Docket SEL 173

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of )  
Ohtani et al. )  
Serial No.: 09/535,836 )  
Filed: March 28, 2000 )  
For: Semiconductor Device Having )  
Multi-layer Wiring )  
Art Unit: 2811 )  
Examiner: H. Vu )

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:  
the Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450 on

MAY 21, 2003

(Date of Deposit)

Shannon Wallace

Name of applicant, assignee, or Registered Rep.

Shannon Wallace 5/21/03

Signature

Date

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT F (AFTER FINAL)**

Sir:

In response to the Final Rejection dated January 22, 2003, a one month extension of time being separately submitted, please enter the following amendment in the above identified application:

**IN THE CLAIMS:**

Please amend the claims as follows:

1. (Third Amendment) A semiconductor device comprising:  
a first insulating film comprising an organic material formed over a conductive layer;  
a first metallic layer formed on said first insulating film;  
a second metallic layer formed on said first metallic layer;  
a second insulating film formed on said second metallic layer; and